



## Initial Product/Process Change Notification

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|                                                                                                                                                                                                                |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
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| <b>Title of Change:</b>                                                                                                                                                                                        | Qualification for SO8FL and u8FL Package from Mold Compound G700LS to G700LAE                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |                |
| <b>Proposed First Ship date:</b>                                                                                                                                                                               | 28 Feb 2027 or earlier if approved by customer                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |                |
| <b>Contact Information:</b>                                                                                                                                                                                    | Contact your local onsemi Sales Office                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |                |
| <b>PCN Samples Contact:</b>                                                                                                                                                                                    | Contact your local onsemi Sales Office.<br>Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.<br>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.                                                                                                                                                                                                                                                                                                                                                                            |                |
| <b>Type of Notification:</b>                                                                                                                                                                                   | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> > |                |
| <b>Marking of Parts/ Traceability of Change:</b>                                                                                                                                                               | No change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |                |
| <b>Change Category:</b>                                                                                                                                                                                        | Assembly Change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
| <b>Change Sub-Category(s):</b>                                                                                                                                                                                 | Material Change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
| <b>Sites Affected:</b>                                                                                                                                                                                         |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
| <b>onsemi Sites</b>                                                                                                                                                                                            | <b>External Foundry/Subcon Sites</b>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |                |
| onsemi Seremban, Malaysia                                                                                                                                                                                      | None                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |                |
| <b>Description and Purpose:</b>                                                                                                                                                                                |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
| onsemi wishes to inform customers of its plan to implement a mold compound material change for selected SO8FL and Ultra-Thin 8-Lead Flat Lead packages assembled at its Seremban, Malaysia manufacturing site. |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
|                                                                                                                                                                                                                | <b>From</b>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  | <b>To</b>      |
| <b>Mold Compound</b>                                                                                                                                                                                           | <b>G700LS</b>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                | <b>G700LAE</b> |
| The change does not impact form, fit, function, product marking, or traceability and is supported by a full qualification plan.                                                                                |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |
| There is no product marking change as a result of this change                                                                                                                                                  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |                |

## Qualification Plan:

**QV DEVICE NAME : NVMFD6H840NLT1G**

**RMS: 101329**

**PACKAGE: SO8FL Dual (T8)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFD040N10MCLT1G**

**RMS: 102365**

**PACKAGE: SO8FL Dual (PTNG)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS3D6N10MCLT1G**

**RMS: 101197**

**PACKAGE: SO8FL HD (PTNG)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS5C604NLAFT1G**

**RMS: 101842**

**PACKAGE: SO8FL HD (T6)**

| Test                                        | Specification                      | Condition                                  | Interval  |
|---------------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias               | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias                  | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life               | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                             | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life                 | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                         | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| High Humidity High Temperature Reverse Bias | JESD22-A101                        | 85°C, 85% RH, bias                         | 1008 hrs  |
| Unbiased Highly Accelerated Stress Test     | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat                   | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                               | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                          | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS6H800NWFT1G**

**RMS: 104471**

**PACKAGE: SO8FL HD (T8)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTFS6H850NLWFTAG**

**RMS: 104474**

**PACKAGE: u8FL (T8)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTFS9D6P04M8LTAG**

**RMS: 102571**

**PACKAGE: u8FL (MV8)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -65°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : MBR8170TFSTXG**

**RMS: 102572**

**PACKAGE: u8FL (Schottky)**

| Test                                        | Specification                      | Condition                                  | Interval  |
|---------------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias               | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Storage Life               | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                             | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life                 | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                         | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| High Humidity High Temperature Reverse Bias | JESD22-A101                        | 85°C, 85% RH, bias                         | 1008 hrs  |
| Unbiased Highly Accelerated Stress Test     | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat                   | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                               | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                          | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NTMFS002P03P8ZST1G**

**RMS: 104088**

**PACKAGE: SO8FL HD (PT8P)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=150°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=150°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 150°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NRVB30H100MFST3G**

**RMS: 102309**

**PACKAGE: SO8FL HD (Schottky Planar)**

| Test                                        | Specification                      | Condition                                  | Interval  |
|---------------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias               | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Storage Life               | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                             | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life                 | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                         | JESD22-A104                        | Ta= -65°C to +150°C, mount form air to air | 1000 cyc  |
| High Humidity High Temperature Reverse Bias | JESD22-A101                        | 85°C, 85% RH, bias                         | 1008 hrs  |
| Unbiased Highly Accelerated Stress Test     | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat                   | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                               | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                          | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NRVTS30120MFST3G**

**RMS: 107925**

**PACKAGE: SO8FL HD (Trench Schottky)**

| Test                                        | Specification                      | Condition                                  | Interval  |
|---------------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias               | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Storage Life               | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                             | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life                 | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                         | JESD22-A104                        | Ta= -65°C to +150°C, mount form air to air | 1000 cyc  |
| High Humidity High Temperature Reverse Bias | JESD22-A101                        | 85°C, 85% RH, bias                         | 1008 hrs  |
| Unbiased Highly Accelerated Stress Test     | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat                   | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                               | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                          | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS5832NLWFT1G**

**RMS: 105752**

**PACKAGE: SO8FL HD (T2)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS5113PLWFT1G**

**RMS: 107924**

**PACKAGE: SO8FL HD (T1)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : MBR30170MFST1G**

**RMS: 110767**

**PACKAGE: SO8FL HD (Schottky Diode)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -65°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |



**QV DEVICE NAME : NVTFWS015P03P8ZTAG**

**RMS: 106678**

**PACKAGE: u8FL (PT8P)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTFWS002N04CLTAG**

**RMS: 106421**

**PACKAGE: u8FL (T6)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTFWS027N10MCLTAG**

**RMS: 106696**

**PACKAGE: u8FL (PTNG)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTF5010N10MCLTAG**

**RMS: 106696**

**PACKAGE: u8FL (PTNG)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTF55116PLWFTAG**

**RMS: 105753**

**PACKAGE: u8FL (T1)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NRVHP820MFD1G**

**RMS: TBD**

**PACKAGE: SO8FL Dual (Rect Ultrafast)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFD5873NLWFT1G-UM**

**RMS: TBD**

**PACKAGE: SO8FL Dual (T2)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFD5C650NLT1G-01**

**RMS: TBD**

**PACKAGE: SO8FL Dual (T6)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NTMFS0D8N02P1ET1G**

**RMS: TBD**

**PACKAGE: SO8FL HD (PT11E)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVMFS9D6P04M8LT1G**

**RMS: TBD**

**PACKAGE: SO8FL HD (MV8)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NVTF55826NLWFTWG**

**RMS: TBD**

**PACKAGE: u8FL (T2)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Gate Bias              | JESD22-A108                        | Ta=175°C, 100% max rated Vgss              | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NRTS6100TFSTAG**

**RMS: TBD**

**PACKAGE: u8FL (Trench Schottky)**

| Test                                    | Specification                      | Condition                                  | Interval  |
|-----------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias           | JESD22-A108                        | Ta=175°C, 100% max rated V                 | 1008 hrs  |
| High Temperature Storage Life           | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                         | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life             | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                     | JESD22-A104                        | Ta= -55°C to +150°C, mount form air to air | 1000 cyc  |
| Highly Accelerated Stress Test          | JESD22-A110                        | 130°C, 85% RH, 18.8psig, bias              | 96 hrs    |
| Unbiased Highly Accelerated Stress Test | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat               | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                           | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                      | JESD22-B120                        |                                            |           |

**QV DEVICE NAME : NRVTS30120MFST3G**

**RMS: 107925**

**PACKAGE: SO8FL HD (Trench Schottky)**

| Test                                        | Specification                      | Condition                                  | Interval  |
|---------------------------------------------|------------------------------------|--------------------------------------------|-----------|
| High Temperature Reverse Bias               | JESD22-A108                        | Ta=90°C, 100% max rated V                  | 1008 hrs  |
| High Temperature Storage Life               | JESD22-A103                        | Ta= 175°C                                  | 1008 hrs  |
| Preconditioning                             | J-STD-020 JESD-A113                | MSL 1 @ 260 °C                             |           |
| Intermittent Operating Life                 | MIL-STD-750<br>(M1037)<br>AEC-Q101 | Ta=+25°C, delta Tj=100°C<br>On/off = 2 min | 15000 cyc |
| Temperature Cycling                         | JESD22-A104                        | Ta= -65°C to +150°C, mount form air to air | 1000 cyc  |
| High Humidity High Temperature Reverse Bias | JESD22-A101                        | 85°C, 85% RH, bias                         | 1008 hrs  |
| Unbiased Highly Accelerated Stress Test     | JESD22-A118                        | 130°C, 85% RH, 18.8psig, unbiased          | 96 hrs    |
| Resistance to Solder Heat                   | JESD22- B106                       | Ta = 265°C, 10 sec                         |           |
| Solderability                               | JSTD002                            | Ta = 245°C, 5 sec                          |           |
| Physical Dimension                          | JESD22-B120                        |                                            |           |

Estimated date for qualification completion: **30 August 2026**

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Current Part Number | New Part Number | Qualification Vehicle |
|---------------------|-----------------|-----------------------|
| NTMFD5C446NLT1G     | #NONE           | NVMFD5C650NLT1G-01    |
| NTMFD5C672NLT1G     | #NONE           | NVMFD5C650NLT1G-01    |
| NTMFD5C674NLT1G     | #NONE           | NVMFD5C650NLT1G-01    |
| NTMFS016N06CT1G     | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C06NCT1G      | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C09NCT1G      | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C10NCT1G      | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C55NT1G       | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C59NT1G       | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS4C908NAT3G     | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS5113PLT1G      | #NONE           | NVMFS5113PLWFT1G      |
| NTMFS5C426NLT1G     | #NONE           | NVMFS5C604NLAFT1G     |
| NTMFS5C450NLT1G     | #NONE           | NVMFS5C604NLAFT1G     |



## Initial Product/Process Change Notification

Document #: IPCN26343X

Issue Date: 09 Jul 2026

|                   |       |                    |
|-------------------|-------|--------------------|
| NTMFS5C456NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C468NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C604NLT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C646NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C670NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C673NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTTFS002N04CLTAG  | #NONE | NRVTS30100MFST3G   |
| NTTFS004N04CTAG   | #NONE | NRVTS30100MFST3G   |
| NTTFS5C460NLTAG   | #NONE | NVTFWS002N04CLTAG  |
| NTTFS5C454NLTAG   | #NONE | NVTFWS002N04CLTAG  |
| NTTFS5C453NLTWG   | #NONE | NVTFWS5826NLWFTWG  |
| NTTFS5C453NLTAG   | #NONE | NVTFWS5826NLWFTWG  |
| NTTFS4C13NTAG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS4C10NTAG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS4C08NTWG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS4C06NTAG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS4C02NTAG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS015P03P8ZTAG | #NONE | NVTFWS027N10MCLTAG |
| NTTFS015N04CTAG   | #NONE | NVTFWS027N10MCLTAG |
| NTTFS012N10MDTAG  | #NONE | NVTFWS027N10MCLTAG |
| NTTFS010N10MCLTAG | #NONE | NRVTS30100MFST3G   |
| NTTFS008N04CTAG   | #NONE | NRVTS30100MFST3G   |
| NTTFS005N04CTAG   | #NONE | NRVTS30100MFST3G   |
| NTTFS002N04CTAG   | #NONE | NRVTS30100MFST3G   |
| NTMFS5C682NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C677NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C673NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C670NLT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C670NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C646NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C645NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C628NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C628NLT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C628NLT1G   | #NONE | NVMFS5C604NLAFT1G  |





## Initial Product/Process Change Notification

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|                   |       |                    |
|-------------------|-------|--------------------|
| NTMFS5C604NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C460NLT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C460NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C442NLT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C430NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C406NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C406NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5C404NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4D2N10MDT1G  | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS4C910NBT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C910NAT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C906NBT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C905NAT3G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C324NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C302NT3G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C302NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C13NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C10NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C09NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C08NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C05NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C029NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C028NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS4C025NT1G    | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS3D6N10MCLT1G | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS3D2N10MDT1G  | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS1D15N03CGT1G | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS0D8N02P1ET1G | #NONE | NTMFS0D8N02P1ET1G  |
| NTMFS0D7N03CGT1G  | #NONE | NTMFS005P03P8ZST1G |
| NTMFS0D6N03CT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS0D5N03CT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS0D55N03CGT1G | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS024N06CT1G   | #NONE | NTMFS0D8N02P1ET1G  |
| NTMFS020N06CT1G   | #NONE | NTMFS0D8N02P1ET1G  |



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|                    |       |                    |
|--------------------|-------|--------------------|
| NTMFS015N10MCLT1G  | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS008N12MCT1G   | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS006N12MCT1G   | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS005P03P8ZT1G  | #NONE | NTMFS005P03P8ZST1G |
| NTMFS005P03P8ZST1G | #NONE | NTMFS005P03P8ZST1G |
| NTMFS005N10MCLT1G  | #NONE | NTMFS005P03P8ZST1G |
| NTMFS003P03P8ZT1G  | #NONE | NTMFS005P03P8ZST1G |
| NTMFS002P03P8ZT1G  | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFS002N10MCLT1G  | #NONE | NVMFS3D6N10MCLT1G  |
| NTMFD5C680NLT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD5C478NLT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD5C466NT1G     | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD5C466NLT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD030N06CT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD024N06CT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD020N06CT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NTMFD016N06CT1G    | #NONE | NVMFD5C650NLT1G-01 |
| NRTS6100TFSTXG     | #NONE | NRTS6100TFSTAG     |
| NRTS6100TFSTAG     | #NONE | NRTS6100TFSTAG     |
| NRTS3060MFST3G     | #NONE | NRVTS30100MFST3G   |
| NRTS30120MFST3G    | #NONE | NRVTS30100MFST3G   |
| NTTFS030N10GTAG    | #NONE | NVTFWS002N04CLTAG  |
| NTTFS030N06CTAG    | #NONE | NVTFWS002N04CLTAG  |
| NTTFS024N06CTAG    | #NONE | NVTFWS002N04CLTAG  |
| NTTFS020N06CTAG    | #NONE | NVTFWS027N10MCLTAG |
| NTTFS016N06CTAG    | #NONE | NVTFWS027N10MCLTAG |
| NTTFS015P03P8ZTWG  | #NONE | NVTFWS027N10MCLTAG |
| NTMFS5C404NT1G     | #NONE | NVMFS5C604NLAFT1G  |
| NTMFS5CS628NLT1G   | #NONE | NVMFS5C604NLAFT1G  |
| NRTS6100TFSTWG     | #NONE | NRTS6100TFSTAG     |
| NRTS6100TFSTBG     | #NONE | NRTS6100TFSTAG     |
| NTTFS5116PLTWG     | #NONE | NVTFWS5116PLWFTAG  |
| NTTFS5116PLTAG     | #NONE | NVTFWS002N04CLTAG  |
| NTTFS4C50NTAG      | #NONE | NVTFWS002N04CLTAG  |



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|                 |       |                    |
|-----------------|-------|--------------------|
| MBR2045MFST1G   | #NONE | MBR30170MFST1G     |
| MBR30170MFST1G  | #NONE | MBR30170MFST1G     |
| MBR30170MFST3G  | #NONE | MBR30170MFST1G     |
| MBR30H100MFST3G | #NONE | MBR30170MFST1G     |
| MBR460MFST1G    | #NONE | MBR30170MFST1G     |
| MBR5H100MFST1G  | #NONE | MBR30170MFST1G     |
| MBR8170TFSTAG   | #NONE | MBR8170TFSTXG      |
| MBR8170TFSTBG   | #NONE | MBR8170TFSTXG      |
| MBR8170TFSTWG   | #NONE | MBR8170TFSTXG      |
| MBR8170TFSTXG   | #NONE | MBR8170TFSTXG      |
| MBR8H100MFST1G  | #NONE | MBR30170MFST1G     |
| NHP620MFD1G     | #NONE | NRVHP820MFD1G      |
| NRTS30100MFST3G | #NONE | NRVTS30100MFST3G   |
| NTTF55C466NLTAG | #NONE | NVTFWS002N04CLTAG  |
| NTTF55C670NLTAG | #NONE | NVTFWS002N04CLTAG  |
| NTTF55C673NLTAG | #NONE | NVTFWS002N04CLTAG  |
| NTTF55C680NLTAG | #NONE | NVTFWS002N04CLTAG  |
| NTTF55C573NLTAG | #NONE | NVTFWS002N04CLTAG  |
| STTF5010N10MCL  | #NONE | NVTFWS002N04CLTAG  |
| STTF5015N10MCL  | #NONE | NVTFWS027N10MCLTAG |
| STTF55C658NLTAG | #NONE | NVTFWS002N04CLTAG  |
| NTTF54C025NTAG  | #NONE | NVTFWS002N04CLTAG  |
| NTTF5080N10GTAG | #NONE | NVTFWS027N10MCLTAG |

**PCN Product List Addendum for:**

**Customer Contact Name:** Premier Farnell Dropbox

**Customer Contact Email:** [productchangenotices@newark.com](mailto:productchangenotices@newark.com)

## Appendix A: Changed Products

PCN#: IPCN26343X  
Issue Date: Jul 09, 2026

NWKC: PREMIER FARNELL

| Product           | Customer Part Number | Qualification Vehicle | New Part Number | Replacement Supplier |
|-------------------|----------------------|-----------------------|-----------------|----------------------|
| NTMFD5C672NLT1G   | 4317969              | NVMFD5C650NLT1G-01    | #NONE           |                      |
| NTMFS5C426NLT1G   | 3766211              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFD5C674NLT1G   | 2895695              | NVMFD5C650NLT1G-01    | #NONE           |                      |
| NTMFS5C468NLT1G   | 2706276              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTTFS012N10MDTAG  | 3929797              | NVTFWS027N10MCLTAG    | #NONE           |                      |
| NTMFS5C456NLT1G   | 2706273              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTTFS4C06NTAG     | 2724425              | NVTFWS002N04CLTAG     | #NONE           |                      |
| NTMFS5C670NLT1G   | 2508376              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS5C628NLT1G   | 2706272              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS5C646NLT1G   | 2452047              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS5C604NLT1G   | 2452046              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS5C460NLT1G   | 2706274              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS4C910NBT1G   |                      | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS4C09NT1G     | 2473413              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS4C05NT1G     | 2473411              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS4D2N10MDT1G  | 3677730              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS4C906NBT1G   | 4036818              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS4C08NT1G     | 2630358              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS3D6N10MCLT1G | 3528507              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS0D8N02P1ET1G | 3464009              | NTMFS0D8N02P1ET1G     | #NONE           |                      |
| NTMFS3D2N10MDT1G  | 3929793              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS0D5N03CT1G   | 3677726              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS0D6N03CT1G   | 3677727              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTMFS015N10MCLT1G | 3528505              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS005P03P8ZT1G | 4381448              | NTMFS005P03P8ZST1G    | #NONE           |                      |
| NTMFS005N10MCLT1G | 3677724              | NTMFS005P03P8ZST1G    | #NONE           |                      |
| NTMFS006N12MCT1G  | 3677725              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS002P03P8ZT1G | 3766208              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFD5C680NLT1G   | 2895709              | NVMFD5C650NLT1G-01    | #NONE           |                      |
| NTTFS5116PLTAG    | 2533205              | NVTFWS002N04CLTAG     | #NONE           |                      |
| NTMFS002N10MCLT1G | 3973629              | NVMFS3D6N10MCLT1G     | #NONE           |                      |
| NTMFS5C404NT1G    | 2677176              | NVMFS5C604NLAFT1G     | #NONE           |                      |
| NTTFS5116PLTAG    | 2985394              | NVTFWS002N04CLTAG     | #NONE           |                      |
| NTTFS5C670NLTAG   | 2563863              | NVTFWS002N04CLTAG     | #NONE           |                      |
| MBR5H100MFST1G    | 2533231              | MBR30170MFST1G        | #NONE           |                      |